



POWER-MOS FET

FIELD EFFECT POWER TRANSISTOR

**IRFD2Z0,2Z1
D82AN2,M2**

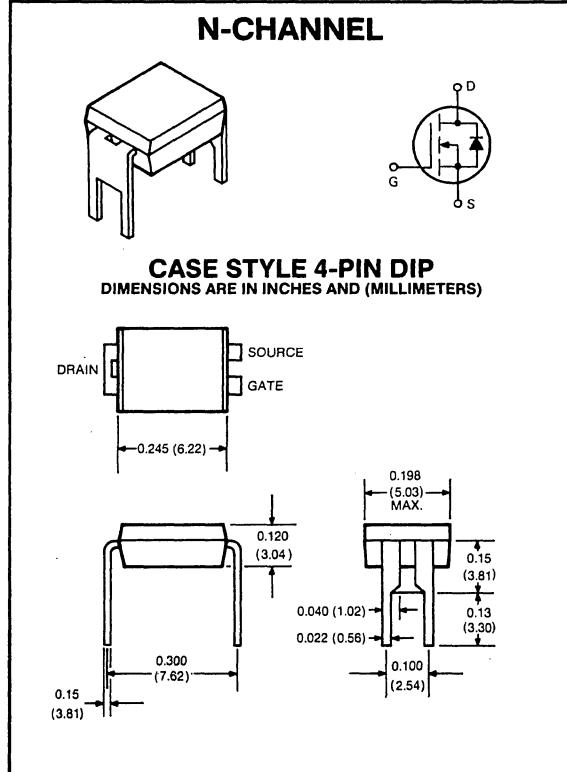
0.32 AMPERES
200, 150 VOLTS
 $R_{DS(ON)} = 5.0 \Omega$

This series of N-Channel Enhancement-mode Power MOSFETs utilizes GE's advanced Power DMOS technology to achieve low on-resistance with excellent device ruggedness and reliability.

This design has been optimized to give superior performance in most switching applications including: switching power supplies, inverters, converters and solenoid/relay drivers. Also, the extended safe operating area with good linear transfer characteristics makes it well suited for many linear applications such as audio amplifiers and servo motors.

Features

- Polysilicon gate — Improved stability and reliability
- No secondary breakdown — Excellent ruggedness
- Ultra-fast switching — Independent of temperature
- Voltage controlled — High transconductance
- Low input capacitance — Reduced drive requirement
- Excellent thermal stability — Ease of paralleling



maximum ratings ($T_A = 25^\circ C$) (unless otherwise specified)

RATING	SYMBOL	IRFD2Z0/D82AN2	IRFD2Z1/D82AM2	UNITS
Drain-Source Voltage	V_{DSS}	200	150	Volts
Drain-Gate Voltage, $R_{GS} = 1M\Omega$	V_{DGR}	200	150	Volts
Continuous Drain Current @ $T_A = 25^\circ C^{(1)}$ @ $T_A = 100^\circ C^{(1)}$	I_D	0.32 0.20	0.32 0.20	A A
Pulsed Drain Current ⁽²⁾	I_{DM}	1.5	1.5	A
Gate-Source Voltage	V_{GS}	± 20	± 20	Volts
Total Power Dissipation @ $T_A = 25^\circ C^{(1)}$ Derate Above 25°C	P_D	1.0 8	1.0 8	Watts W/ $^\circ C$
Operating and Storage Junction Temperature Range	T_J, T_{STG}	-55 to 150	-55 to 150	$^\circ C$

thermal characteristics

Thermal Resistance, Junction to Ambient ⁽¹⁾	$R_{\theta JA}$	125	125	$^\circ C/W$
Maximum Lead Temperature for Soldering Purposes: 1/8" from Case for 5 Seconds	T_L	260	260	$^\circ C$

(1) Device mounted to vertical pc board in free air with drain lead soldered to 0.20 in² minimum copper run area.

(2) Repetitive Rating: Pulse width Limited by Max. Junction Temperature.

electrical characteristics ($T_C = 25^\circ C$) (unless otherwise specified)

CHARACTERISTIC	SYMBOL	MIN	TYP	MAX	UNIT
off characteristics					
Drain-Source Breakdown Voltage ($V_{GS} = 0V$, $I_D = 250 \mu A$)	IRFD2Z0/D82AN2 IRFD2Z1/D82AM2	BVDSS 150	— —	— —	Volts
Zero Gate Voltage Drain Current ($V_{DS} = \text{Max Rating}$, $V_{GS} = 0V$, $T_A = 25^\circ C$) ($V_{DS} = \text{Max Rating} \times 0.8$, $V_{GS} = 0V$, $T_A = 125^\circ C$)	IDS	— —	— —	250 1000	μA
Gate-Source Leakage Current ($V_{GS} = \pm 20V$)	IGSS	—	—	±500	nA

on characteristics*

Gate Threshold Voltage ($V_{DS} = V_{GS}$, $I_D = 1\mu A$)	$T_A = 25^\circ C$	$V_{GS(TH)}$	2.0	—	4.0	Volts
Drain Source On-State Voltage ($V_{GS} = 10V$)	$I_D = 0.15A$ $I_D = 0.32A$ $I_D = 0.15A$, $T_A = 125^\circ C$	$V_{DS(ON)}$	— — —	0.66 1.41 1.05	0.75 — —	Volts
Static Drain-Source On-State Resistance ($V_{GS} = 10V$, $I_D = 0.15A$)		$R_{DS(ON)}$	—	4.4	5.0	Ohms
Forward Transconductance ($V_{DS} = 10V$, $I_D = 0.15A$)		g_{fs}	—	0.11	—	mhos

dynamic characteristics

Input Capacitance	$V_{GS} = 0V$	C_{iss}	—	37	70	pF
Output Capacitance	$V_{DS} = 25V$	C_{oss}	—	15	25	pF
Reverse Transfer Capacitance	$f = 1 MHz$	C_{rss}	—	4	8	pF

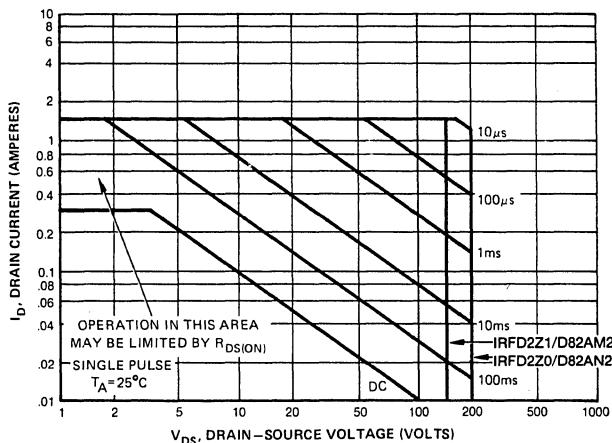
switching characteristics*

Turn-on Delay Time	$V_{DS} = 90V$	$t_{d(on)}$	—	15	—	ns
Rise Time	$I_D = 0.15A$, $V_{GS} = 15V$	t_r	—	10	—	ns
Turn-off Delay Time	$R_{GEN} = 50\Omega$, $R_{GS} = 12.5\Omega$	$t_{d(off)}$	—	22	—	ns
Fall Time	(R_{GS} (EQUIV.) = 10Ω)	t_f	—	28	—	ns

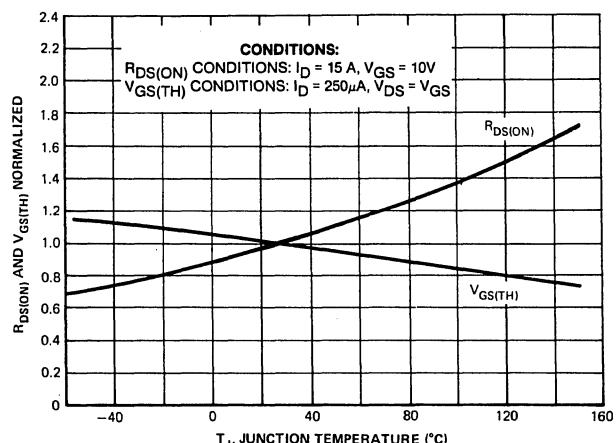
source-drain diode ratings and characteristics*

Continuous Source Current	I_S	—	—	0.32	A
Pulsed Source Current	I_{SM}	—	—	1.5	A
Diode Forward Voltage ($T_A = 25^\circ C$, $V_{GS} = 0V$, $I_S = 0.32A$)	V_{SD}	—	0.86	1.3	Volts
Reverse Recovery Time ($I_S = 0.32A$, $dI_S/dt = 100A/\mu s$, $V_{DS} = 80V$ Max., $T_A = 125^\circ C$)	t_{rr}	—	125	—	ns

*Pulse Test: Pulse width $\leq 300 \mu s$, duty cycle $\leq 2\%$



MAXIMUM SAFE OPERATING AREA



TYPICAL NORMALIZED $R_{DS(ON)}$ AND $V_{GS(TH)}$ VS. TEMP.